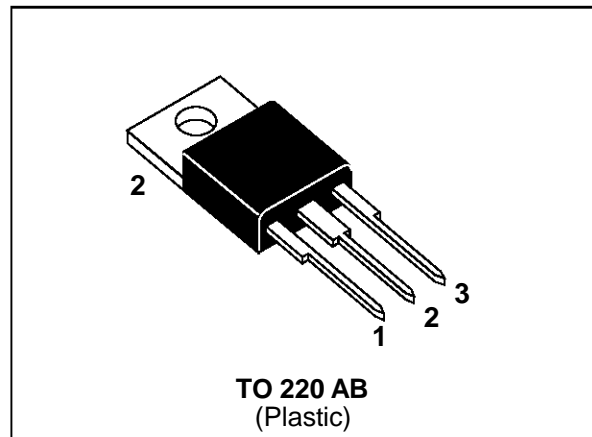


FEATURES

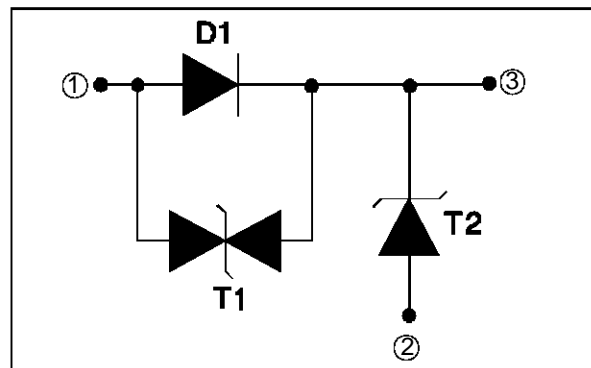
- PROTECTION AGAINST "LOAD DUMP" EFFECT
- DIODE TO GUARD AGAINST BATTERY REVERSAL
- MONOLITHIC STRUCTURE FOR GREATER RELIABILITY
- NEGATIVE OVERVOLTAGE PROTECTION BY CLAMPING (COMPONENT T1)
- BREAKDOWN VOLTAGE : 24 V min
- CLAMPING VOLTAGE : ± 40 V max
- AVERAGE FORWARD DIODE CURRENT : 40 A



DESCRIPTION

Designed to protect against battery reversal and load dump overvoltages in automotive applications, this monolithic component offers multiple functions in the same package :
 D1 : reversed battery protection
 T1 : clamping against negative overvoltages
 T2 : Transil function against "load dump" effect

FUNCTIONAL DIAGRAM



ABSOLUTE MAXIMUM RATINGS (- 40°C < T_{amb} < + 85°C)

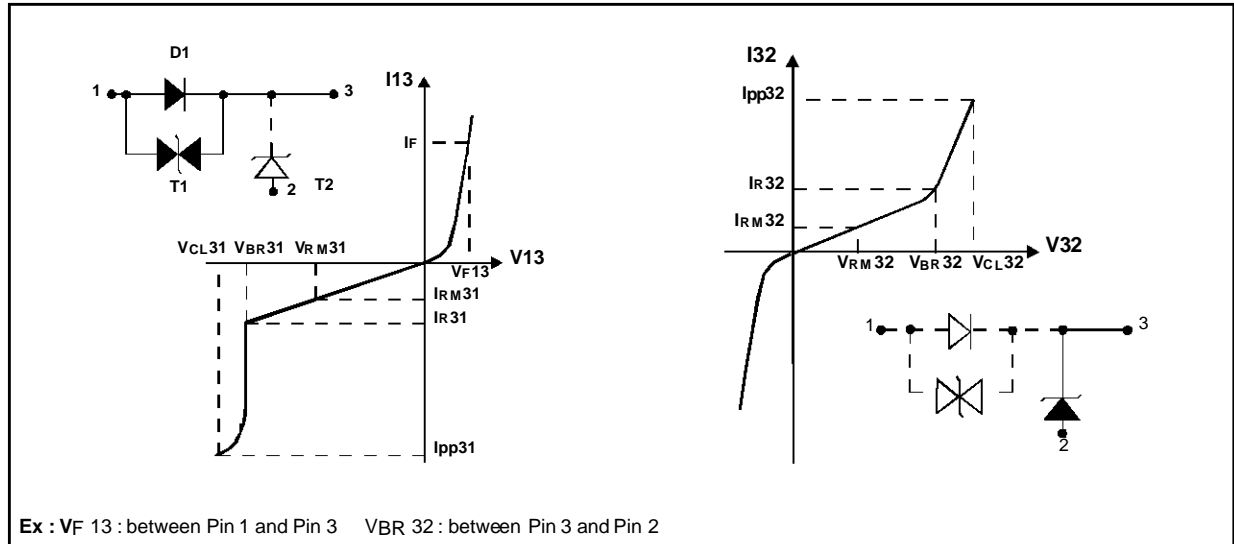
Symbol	Parameter	Value	Unit	
I _{FSM}	Non repetitive surge peak forward current between pins 1 and 3	t _p = 10μs	400	A
		t _p = 10ms	120	
I _{F(AV)}	Average forward current between pins 1 and 3	T _c = 75°C	40	A
V _{PP}	Peak load dump voltage (see note 1 and 2)		80	V
P _P	Peak pulse power between pins 3 and 1	10/1000μs	1500	W
P	Total power dissipation	T _c = 75°C	75	W
T _{stg} T _j	Storage temperature range Maximum operating junction temperature		- 40 to + 150 150	°C
T _l	Maximum lead temperature for soldering during 10s at 4.5 mm from case		260	°C

Note 1 : for a surge greater than the maximum value, the device will fail in short circuit.
Note 2 : see load dump test generator circuit (page 3/7)

RBO40-40T

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1	°C/W
$R_{th(j-a)}$	Junction to ambient	60	°C/W



ELECTRICAL CHARACTERISTICS : DIODE D1 (- 40°C < Tamb < + 85°C) (note 1)

Symbol	Test Conditions	Value			Unit
		Min.	Typ.	Max.	
$V_F 13$	Forward voltage @ $I_F = 40\text{ A}$ $t_p = 380\ \mu\text{s}$			1.9	V
$V_F 13$	Forward voltage @ $I_F = 20\text{ A}$ $t_p = 380\ \mu\text{s}$			1.45	V
$V_F 13$	Forward voltage @ $I_F = 1\text{ A}$ $t_p = 380\ \mu\text{s}$			1	V
$V_F 13$	Forward voltage @ $I_F = 100\text{ mA}$ $t_p = 380\ \mu\text{s}$			0.95	V
C_{13}	Capacitance at 0 V		3000		pF

Note 1 : "13", "31" and "32" suffixes :

ELECTRICAL CHARACTERISTICS : TRANSIL T1 (- 40°C < Tamb < + 85°C) (note 1)

$V_{BR} 31$	Breakdown voltage @ $I_R = 1\text{ mA}$	22		35	V
$V_{BR} 31$	Breakdown voltage @ $I_R = 1\text{ mA}$ $T_{amb} = 25^\circ\text{C}$	24		32	V
$I_{RM} 31$	Leakage current @ $V_{RM} = 20\text{ V}$			300	μA
$I_{RM} 31$	Leakage current @ $V_{RM} = 20\text{ V}$ $T_{amb} = 25^\circ\text{C}$			50	μA
$V_{CL} 31$	Clamping voltage @ $I_{PP} = 37.5\text{ A}$ $10/1000\ \mu\text{s}$			40	V
αT	Temperature coefficient		8.5		$10^{-4}/^\circ\text{C}$

Note 1 : "13", "31" and "32" suffixes :

ELECTRICAL CHARACTERISTICS : TRANSIL T2 (- 40°C < Tamb < + 85°C) (note 1)

V _{BR 32}	Breakdown voltage @ I _R = 1 mA	22		35	V
V _{BR 32}	Breakdown voltage @ I _R = 1 mA Tamb = 25°C	24		32	V
I _{RM 32}	Leakage current @ V _{RM} = 20 V			100	μA
I _{RM 32}	Leakage current @ V _{RM} = 20 V Tamb = 25°C			10	μA
V _{CL 32}	Clamping voltage @ IPP = 20 A (note 2)			40	V
α T	Temperature coefficient		8.5		10 ⁻⁴ /°C
C ₃₂	Capacitance at 0 V		8000		pF

Note 1 : "13", "31" and "32" suffixes :

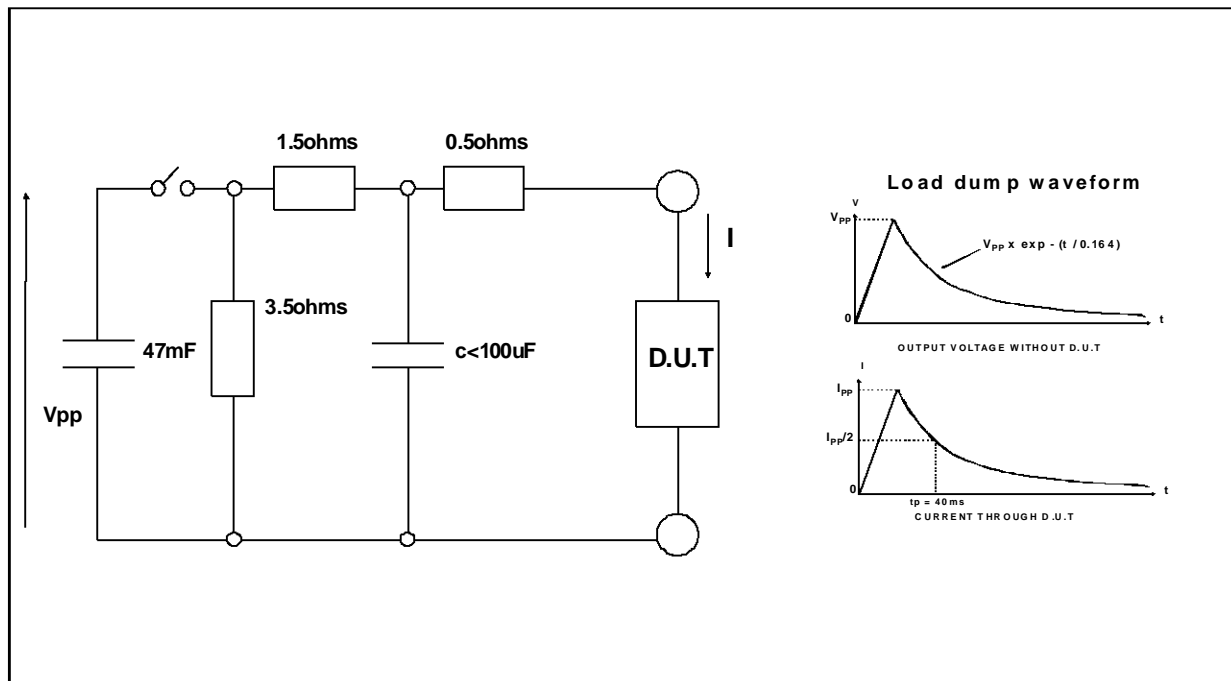
13 = between pin 1 and pin 3.

31 = between pin 3 and pin 1.

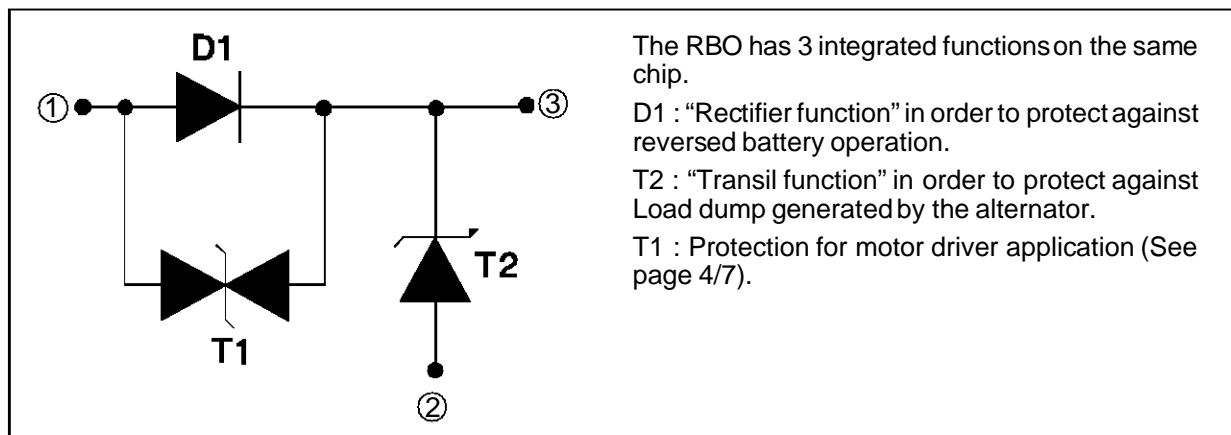
32 = between pin 3 and pin 2.

Note 2 : see below load dump test generator circuit .

LOAD DUMP TEST GENERATOR CIRCUIT (SCHAFFNER NSG 506C)

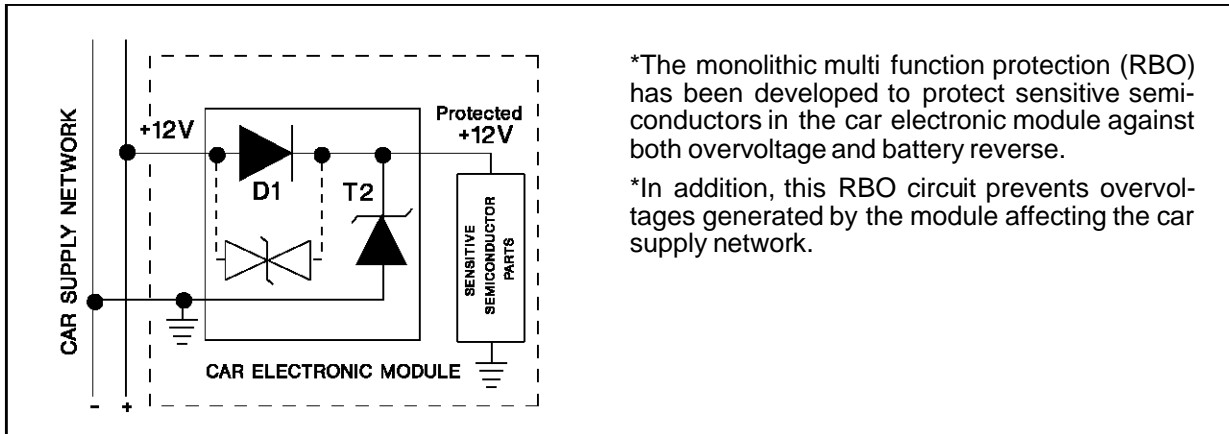


PRODUCT DESCRIPTION



RBO40-40T

BASIC APPLICATION



MOTOR DRIVER APPLICATION

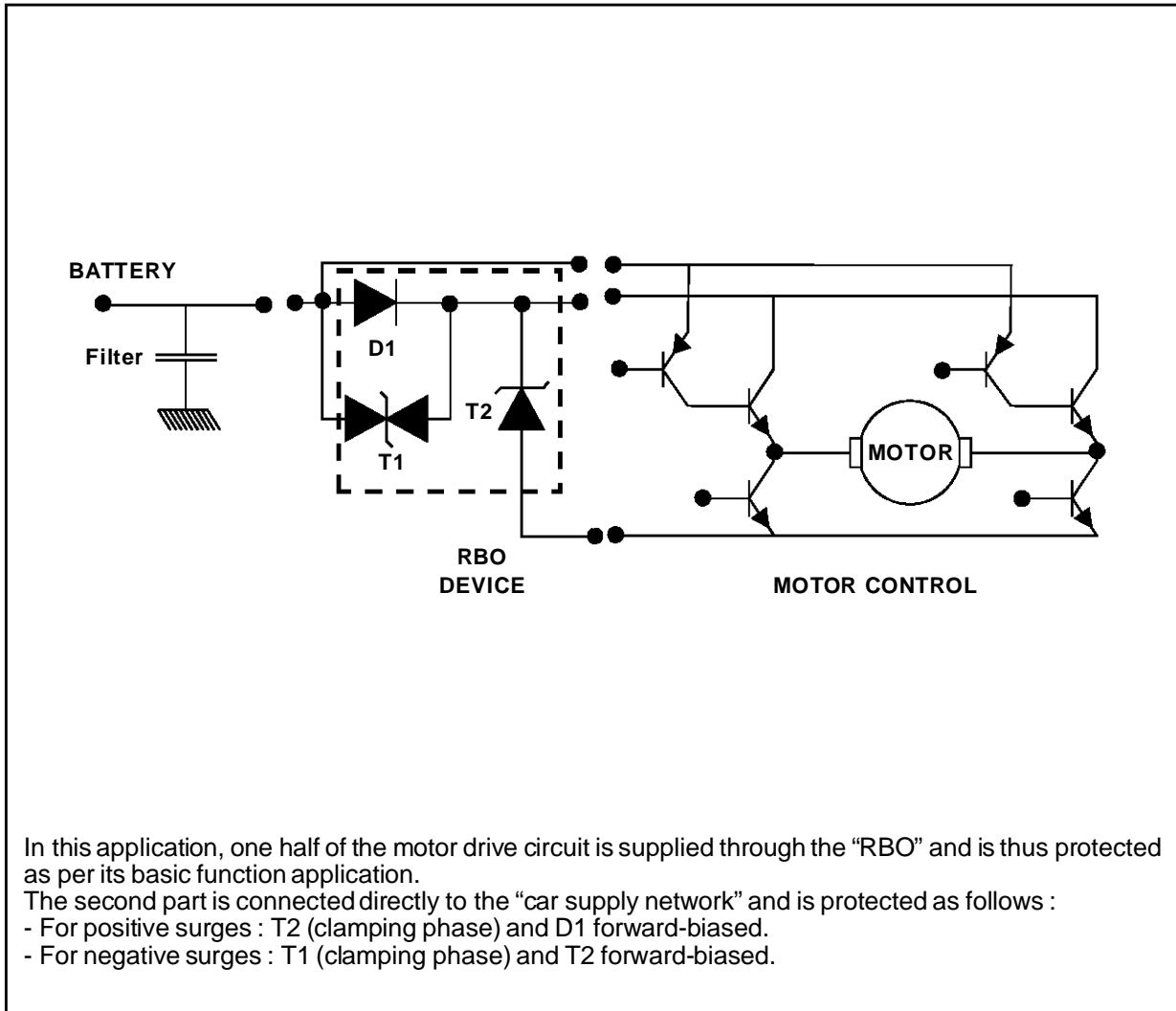


Fig. 1 : Peak pulse power versus exponential pulse duration (T_j initial = 85°C).

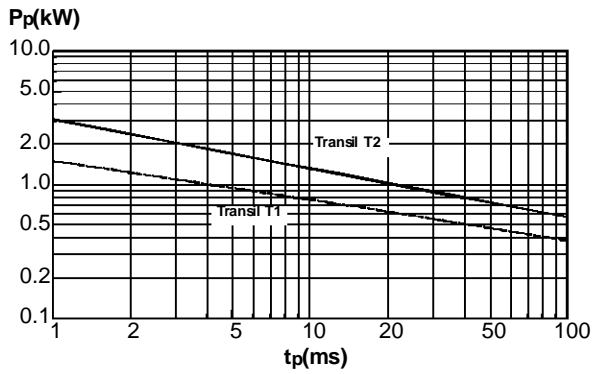


Fig. 2-1 : Clamping voltage versus peak pulse current (T_j initial = 85°C).

Exponential waveform $t_p = 40$ ms and $t_p = 1$ ms (TRANSIL T2).

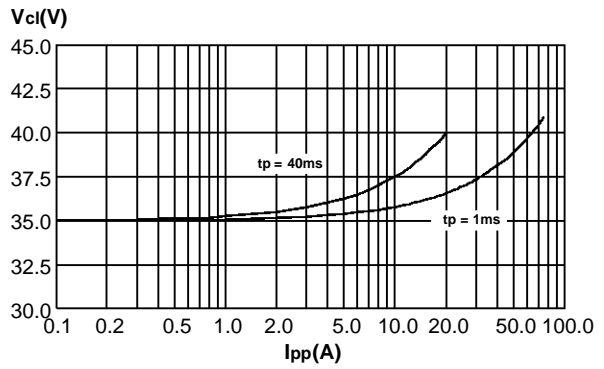


Fig. 2-2 : Clamping voltage versus peak pulse current (T_j initial = 85°C).

Exponential waveform $t_p = 1$ ms and $t_p = 20 \mu s$ (TRANSIL T1).

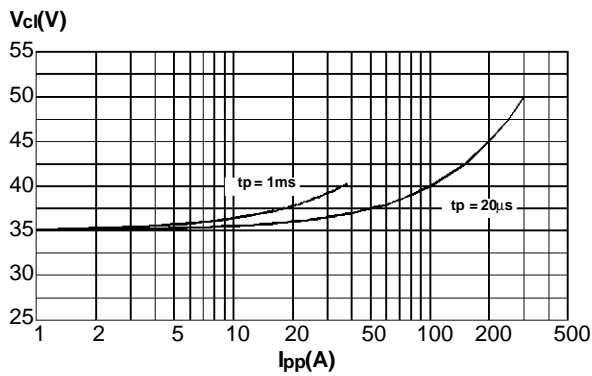


Fig. 3 : Relative variation of peak pulse power versus junction temperature.

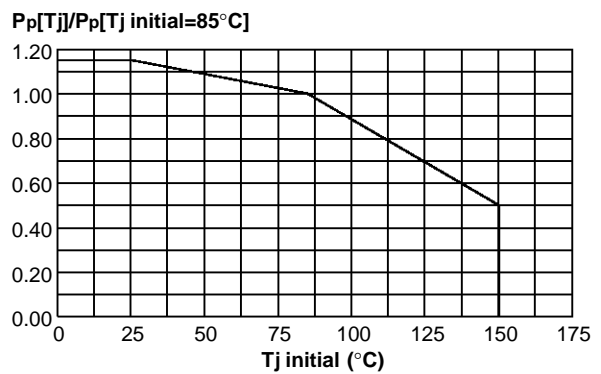


Fig. 4 : Relative variation of thermal impedance junction to case versus pulse duration.

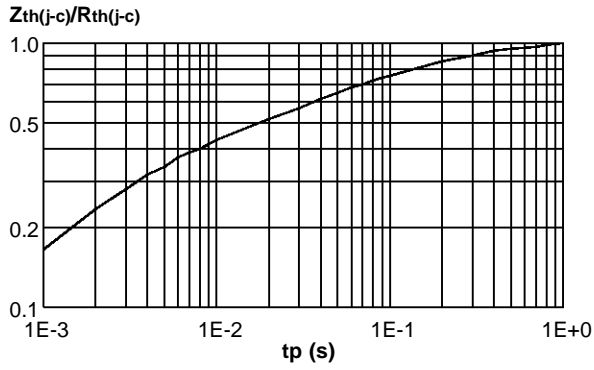


Fig. 5-1 : Peak forward voltage drop versus peak forward current (typical values) - (TRANSIL T2).

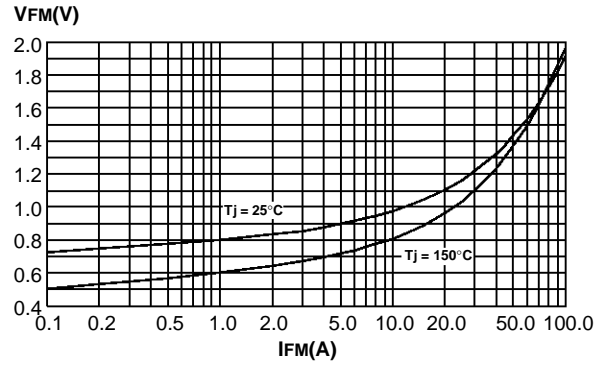
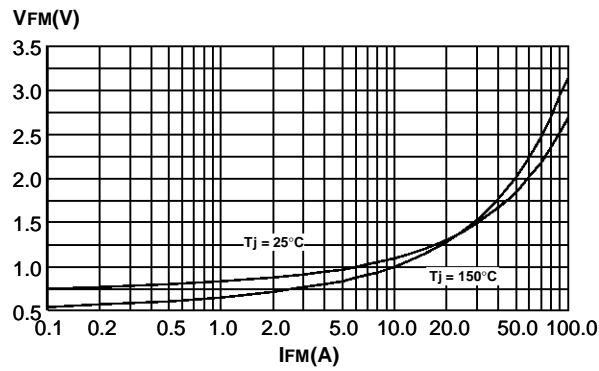
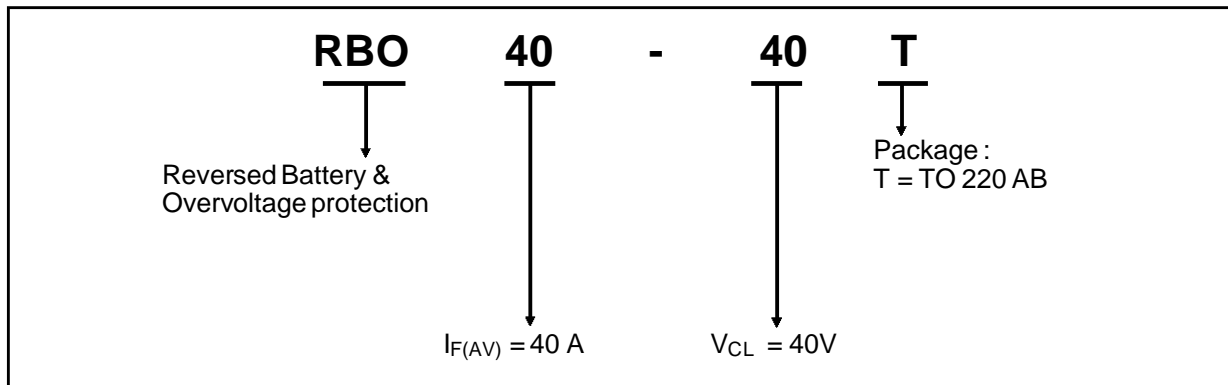


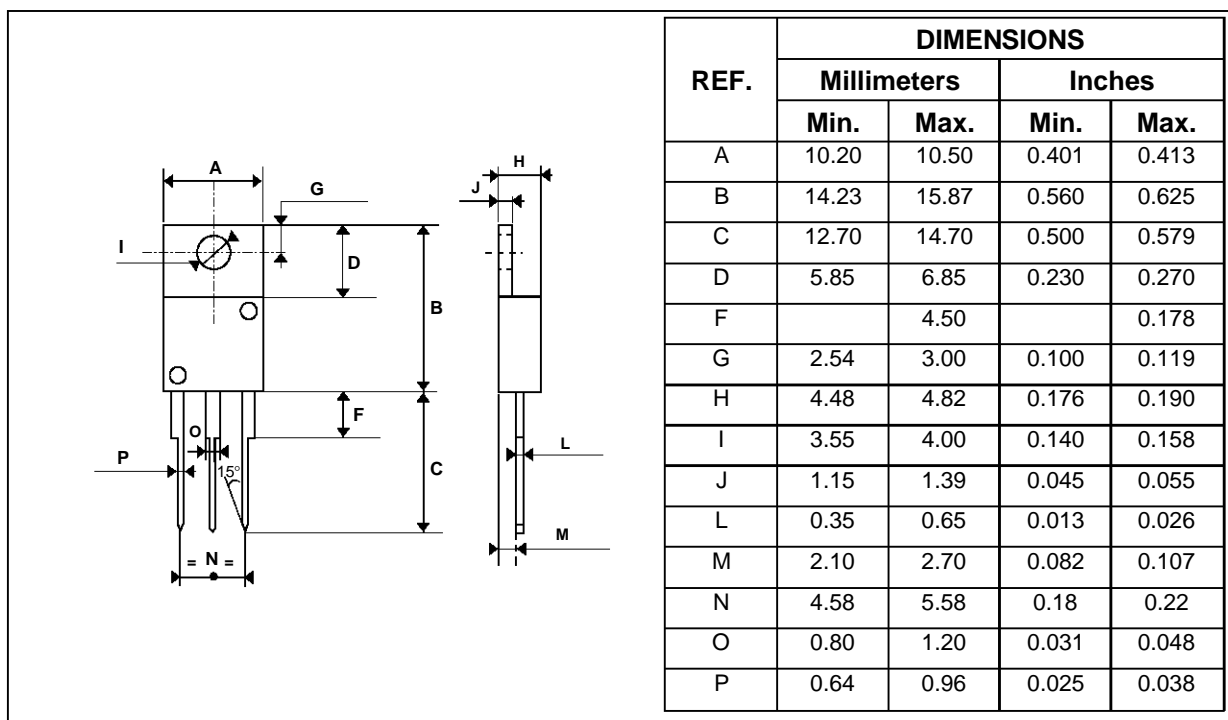
Fig. 5-2 : Peak forward voltage drop versus peak forward current (typical values) - (DIODE D1).



ORDERING INFORMATION



PACKAGE MECHANICAL DATA
TO220AB Plastic



Cooling method : C
 Marking : type number
 Weight : 2 g
 Polarity : N A
 Stud torque : N A

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